

## Announcement and Call for Abstracts

# Advanced Technology Workshop on RF and Microwave Packaging

[www.imaps.org/rf](http://www.imaps.org/rf)

**September 16-18, 2008**

The Crowne Plaza San Diego's  
2270 Hotel Circle North  
San Diego, CA 92108-2810

*IMAPS SoCal Golf Tournament the morning of September 16, 2008*

**Abstract Deadline: June 13, 2008**

Organizing Committee:		
<b>General Chair</b> Ken Kuang Torrey Hills technologies, LLC kkuang@torreyhillstech.com	<b>Technical Co-Chair:</b> Franklin Kim Kyocera America, Inc. franklin.kim@kyocera.com	<b>Technical Co-Chair:</b> Sean Cahill BridgeWave SeanC@Bridgewave.com
Advisory Committee(alphabetical order):		
Steve Adamson, Asymtek, Inc. Mumtaz Bora, Kyocera Wireless Corporation Ron Barnett, Giga-tronics/Ascor Incorporated Carl Edwards, Space Micro, Inc. Mark Eblen, Kyocera America, Inc. Aicha Elshabini, University of Idaho Murat Goksel, Space Micro, Inc. Bill Ishii, Torrey Hills Technologies, LLC	Guosheng Jiang, China Central South University Wally Johnson, Coorstek, Inc. Ho Young Kim, General Optechs Iris Labadie, Kyocera America, Inc. Lee Levine, IMAPS VP of Technology Junkun Ma, Southeastern Louisiana University Tricia McGough, Norstar Group Walt Napoleon, KL Marketing	David Shields, Component Surfaces, Inc. Ron Thiel, retired Mark Tomei, Kyocera America, Inc. David Virissimo, SPM Ziliang Wang, Nanjing Electronics Device Institute David Zhang, GTSI Corporation Danny Zhu, Jiangsu Dingqi Sci. & Tech. Co. Ltd

### RF and Microwave Packaging Workshop Focus:

The objective of the RF and Microwave Packaging Workshop is to provide a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who work in the area of RF and Microwave packaging technologies. This workshop enables discussion and presentation of the latest RF and Microwave technology.

Abstracts are being requested in the following areas:

Emerging Technologies	New Design/Materials	New Applications
<ul style="list-style-type: none"><li>- 60 GHz Personal Area Network (PAN)</li><li>- Short wave IR packaging</li><li>- Nanopackaging</li><li>- 3D RF/MW</li><li>- New and disruptive technology</li><li>- EMI shielding for RF/MW packaging</li></ul>	<ul style="list-style-type: none"><li>- New power amplifier design beyond LDMOS</li><li>- Thermal management</li><li>- New IR sensors without cooling</li><li>- Plastic RF/MW packaging</li><li>- Lead free</li><li>- RF MEMS</li></ul>	<ul style="list-style-type: none"><li>- High Power Electronics</li><li>- Military / Space / Extreme Environments</li><li>- MEMS/NEMS</li><li>- Biomedical</li><li>- Telecommunications</li><li>- MMIC</li><li>- Automotive</li><li>- SIP</li></ul>

Those wishing to present a paper at the RF and Microwave Packaging Advanced Technology Workshop must submit a 200-300 word abstract electronically **no later June 13, 2008**, using the on-line submittal form at: [www.imaps.org/abstracts.htm](http://www.imaps.org/abstracts.htm). Full written papers are not required; however, an extended abstract of 1-4 pages is due for accepted presenters no later than July 25, 2008.

Please contact Jackki Morris-Joyner by email at [jmorris@imaps.org](mailto:jmorris@imaps.org) or by phone at 202-548-4001 if you have questions.

Accepted papers may be considered for publication in the IMAPS *Journal of Microelectronics and Electronic Packaging*. All Speakers are required to pay a reduced registration fee and are required to attend the entire event.

[www.imaps.org/rf](http://www.imaps.org/rf)